

(12) United States Patent Chung et al.

(10) Patent No.: US 6,680,218 B2

(45) **Date of Patent: Jan. 20, 2004**

(54) FABRICATION METHOD FOR VERTICAL ELECTRONIC CIRCUIT PACKAGE AND SYSTEM

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(*) Notice: Subject to any disclaimer, the term of this

patent is extended or adjusted under 35

U.S.C. 154(b) by 0 days.

(21) Appl. No.: 10/371,659

(22) Filed: Feb. 21, 2003

(65) **Prior Publication Data**

US 2003/0151146 A1 Aug. 14, 2003

Related U.S. Application Data

(62)	Division of application No. 09/897,369, filed on Jul. 2, 2001,
	now Pat. No. 6,555,920.

(51)	Int. Cl. ⁷	Н0	1L 21/44
(52)	U.S. Cl.		438/108

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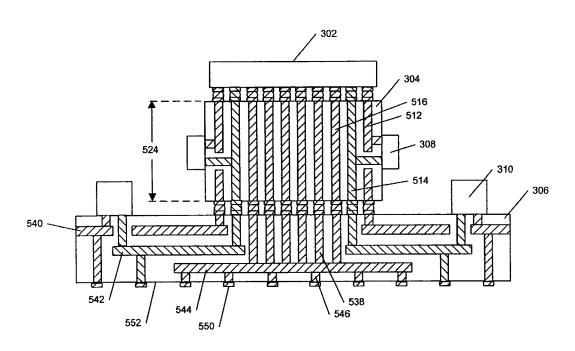
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(57) ABSTRACT

An electronic circuit package includes a vertical package section (304, FIG. 3) electrically connected to a horizontal package section (306, FIG. 3). The vertical package section includes multiple conductive layers (512, 514, 516, FIG. 5) oriented in parallel with a vertical plane. A first set of bond pads (606, FIG. 6) on the vertical section's horizontal top surface (608, FIG. 6) can be connected to the bond pads (602, FIG. 6) of an integrated circuit (302, FIG. 3). A second set of bond pads (612, FIG. 6) on the vertical section's horizontal bottom surface (614, FIG. 6) can be connected to bond pads (616, FIG. 6) on the horizontal package section. The conductive layers of the vertical section perform a bond pad pitch conversion in a first direction, and conductive structures (906, 908, 910, FIG. 9) within the horizontal package section perform a bond pad pitch conversion in a second direction.

21 Claims, 10 Drawing Sheets





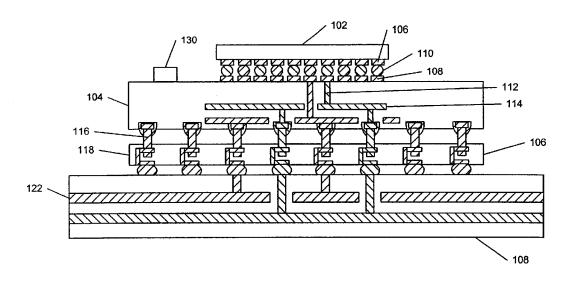


FIG. 1 PRIOR ART

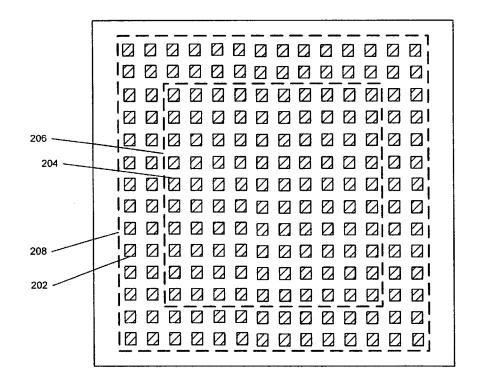
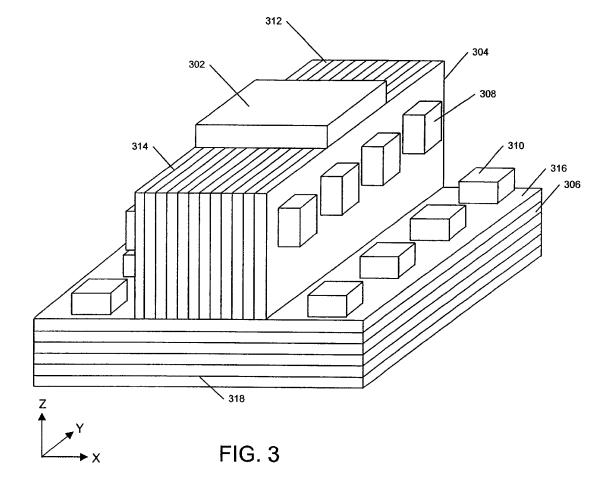


FIG. 2 PRIOR ART





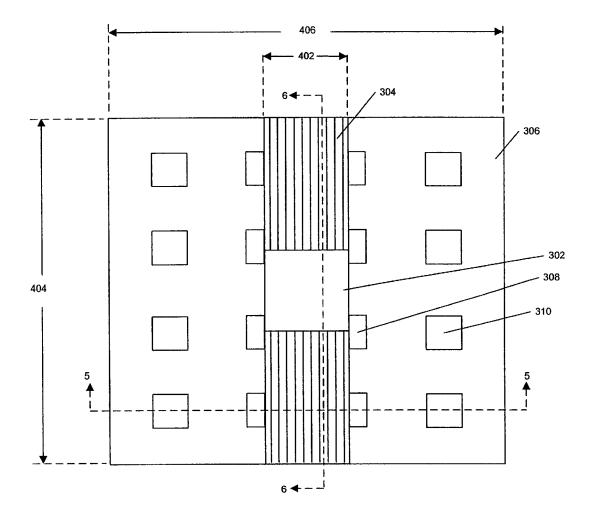


FIG. 4



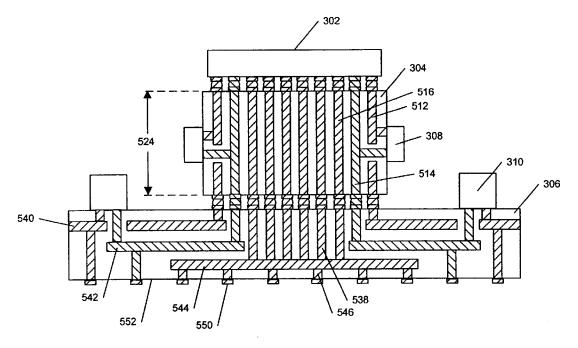


FIG. 5

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